

In the Abstract:

The Abstract, as amended herein, is as follow:

A¹
A flip-chip joinable substrate having non-plated-on contact pads. The substrate has an external metal foil layer upon a dielectric layer upon a patterned internal metal layer having an internal contact area. An area of the external metal foil layer above the internal contact area is selected. A microvia cavity extending to the internal contact area is perforated centrally within the selected area and is filled with a mass of conductive paste forming an external contact pad. The external contact pad is used as an etch mask for removing the adjacent external metal foil.

In the Claims:

Claims 1-6, 9, and 20 are amended herein as marked up in Appendix A. Currently pending claims 1-9 and 20 are as follows:

1. (AMENDED) An electronic structure comprising:

A²
a substrate having a dielectric layer between a first metal layer and a second metal layer, the second metal layer being disposed above the first metal layer, the first metal layer having a first contact area, the second metal layer having a selected area disposed above the first contact area;

a microvia cavity within the selected area being disposed through the second metal layer and through the dielectric layer and extending to the first contact area of the first metal layer; and

a mass of a single conductive material forming a layer upon the selected area of the second metal layer and totally filling the microvia cavity and being in contact with the first